

# IGBT - Field Stop, Trench

650 V, 40 A

## FGH40T65SH

### Description

Using novel field stop IGBT technology, ON Semiconductor's new series of field stop 3<sup>rd</sup> generation IGBTs offer the optimum performance for solar inverter, UPS, welder, telecom, ESS and PFC applications where low conduction and switching losses are essential.

### Features

- Maximum Junction Temperature:  $T_J = 175^{\circ}\text{C}$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(sat)} = 1.6\text{ V(Typ.) @ } I_C = 40\text{ A}$
- 100% of the Parts Tested for  $I_{LM}$  (Note 1)
- High Input Impedance
- Fast Switching
- Tighten Parameter Distribution
- This Device is Pb-Free and is RoHS Compliant

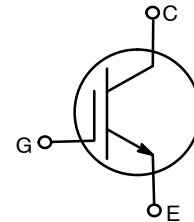
### Applications

- Solar Inverter, UPS, Welder, Telecom, ESS, PFC



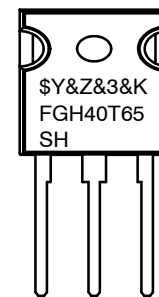
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TO-247-3LD  
CASE 340CH

### MARKING DIAGRAM



\$Y	= ON Semiconductor Logo
&Z	= Assembly Plant Code
&3	= Numeric Date Code
&K	= Lot Code
FGH40T65SH	= Specific Device Code

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# FGH40T65SH

## ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C Unless Otherwise Noted)

Description	Symbol	FGH40T65SH	Unit	
Collector to Emitter Voltage	V <sub>CES</sub>	650	V	
Gate to Emitter Voltage	V <sub>GES</sub>	±20	V	
Transient Gate to Emitter Voltage		±30	V	
Collector Current	I <sub>C</sub>	T <sub>C</sub> = 25°C	80	A
Collector Current		T <sub>C</sub> = 100°C	40	A
Pulsed Collector Current (Note 1)	I <sub>LM</sub>	T <sub>C</sub> = 25°C	120	A
Pulsed Collector Current (Note 2)		I <sub>CM</sub>	120	A
Maximum Power Dissipation	P <sub>D</sub>	T <sub>C</sub> = 25°C	268	W
Maximum Power Dissipation		T <sub>C</sub> = 100°C	134	W
Operating Junction Temperature	T <sub>J</sub>	-55 to +175	°C	
Storage Temperature Range	T <sub>stg</sub>	-55 to +175	°C	
Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds	T <sub>L</sub>	300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- V<sub>CC</sub> = 400 V, V<sub>GE</sub> = 15 V, I<sub>C</sub> = 120 A, R<sub>G</sub> = 41,6 Ω, Inductive Load
- Repetitive Rating: Pulse width limited by max. junction temperature.

## THERMAL CHARACTERISTICS

Parameter	Symbol	FGH40T65SH	Unit
Thermal Resistance, Junction to Case, Max.	R <sub>θJC</sub>	0.56	°C/W
Thermal Resistance, Junction to Ambient, Max.	R <sub>θJA</sub>	40	°C/W

## PACKAGE MARKING AND ORDERING INFORMATION

Top Mark	Part Number	Package	Reel Size	Tape Width	Quantity
FGH40T65SH	FGH40T65SH-F155	TO-247-3LD	-	-	30

## ELECTRICAL CHARACTERISTICS OF THE IGBT (T<sub>C</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Collector to Emitter Breakdown Voltage	BV <sub>CES</sub>	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	650	-	-	V
Temperature Coefficient of Breakdown Voltage	ΔBV <sub>CES</sub> /ΔT <sub>J</sub>	I <sub>C</sub> = 1 mA, Reference to 25°C		0.6		V/°C
Collector Cut-Off Current	I <sub>CES</sub>	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0 V	-	-	250	μA
G-E Leakage Current	I <sub>GES</sub>	V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0 V	-	-	±400	nA

### ON CHARACTERISTICS

G-E Threshold Voltage	V <sub>GE(th)</sub>	I <sub>C</sub> = 40 mA, V <sub>CE</sub> = V <sub>GE</sub>	4.0	5.5	7.5	V
Collector to Emitter Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	-	1.6	2.1	V
		I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V, T <sub>C</sub> = 175°C	-	2.14	-	V

# FGH40T65SH

## ELECTRICAL CHARACTERISTICS OF THE IGBT ( $T_C = 25^\circ\text{C}$ unless otherwise noted) (continued)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	$C_{ies}$	$V_{CE} = 30\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$	–	1995	–	pF
Output Capacitance	$C_{oes}$		–	70	–	pF
Reverse Transfer Capacitance	$C_{res}$		–	23	–	pF
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400\text{ V}, I_C = 40\text{ A},$ $R_G = 6\ \Omega, V_{GE} = 15\text{ V},$ Inductive Load, $T_C = 25^\circ\text{C}$	–	19.2	–	ns
Rise Time	$t_r$		–	34.4	–	ns
Turn-Off Delay Time	$t_{d(off)}$		–	65.6	–	ns
Fall Time	$t_f$		–	9.6	–	ns
Turn-On Switching Loss	$E_{on}$		–	1010	–	$\mu\text{J}$
Turn-Off Switching Loss	$E_{off}$		–	297	–	$\mu\text{J}$
Total Switching Loss	$E_{ts}$		–	1307	–	$\mu\text{J}$
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400\text{ V}, I_C = 40\text{ A},$ $R_G = 6\ \Omega, V_{GE} = 15\text{ V},$ Inductive Load, $T_C = 175^\circ\text{C}$	–	18.4	–	ns
Rise Time	$t_r$		–	32.8	–	ns
Turn-Off Delay Time	$t_{d(off)}$		–	71.2	–	ns
Fall Time	$t_f$		–	14.4	–	ns
Turn-On Switching Loss	$E_{on}$		–	1390	–	$\mu\text{J}$
Turn-Off Switching Loss	$E_{off}$		–	541	–	$\mu\text{J}$
Total Switching Loss	$E_{ts}$		–	1931	–	$\mu\text{J}$
Total Gate Charge	$Q_g$	$V_{CC} = 400\text{ V}, I_C = 40\text{ A},$ $V_{GE} = 15\text{ V}$	–	72.2	–	nC
Gate to Emitter Charge	$Q_{ge}$		–	13.5	–	nC
Gate to Collector Charge	$Q_{gc}$		–	28.5	–	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# FGH40T65SH

## TYPICAL PERFORMANCE CHARACTERISTICS

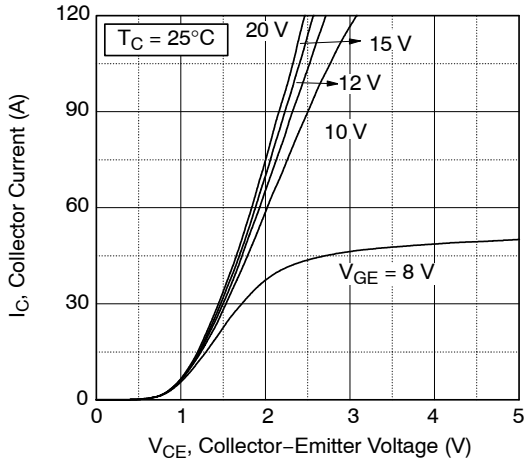


Figure 1. Typical Output Characteristics

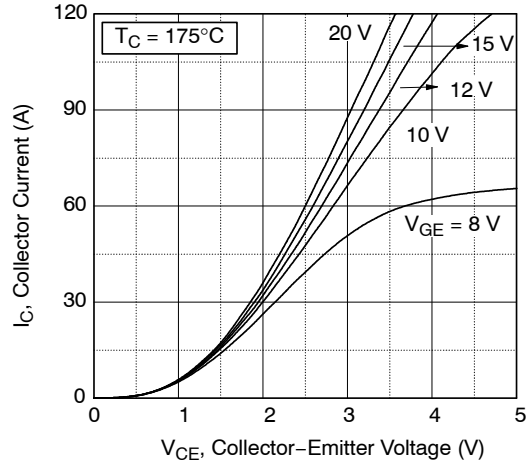


Figure 2. Typical Output Characteristics

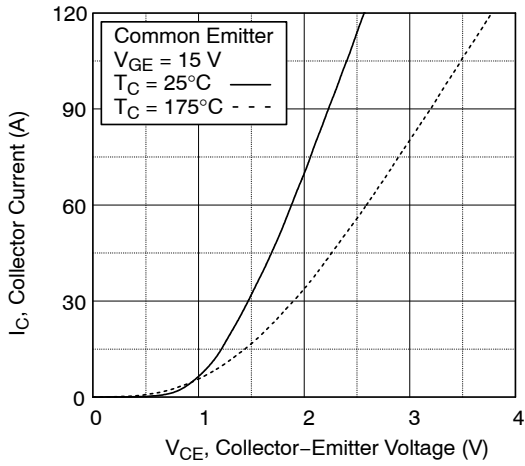


Figure 3. Typical Saturation Voltage Characteristics

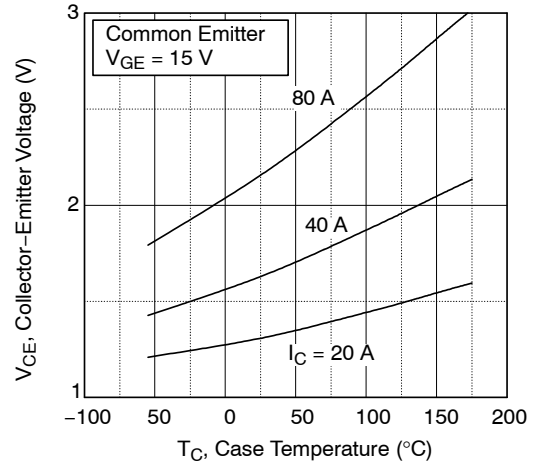


Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level

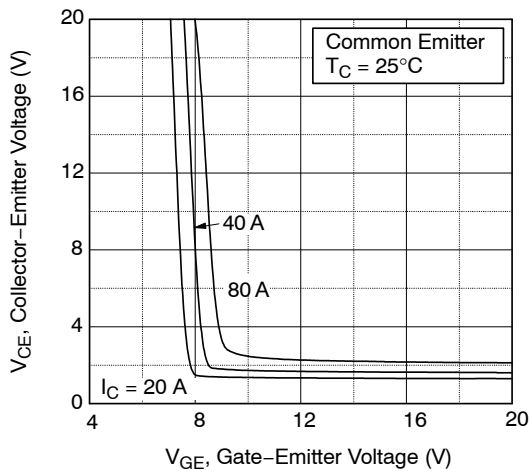


Figure 5. Saturation Voltage vs  $V_{GE}$

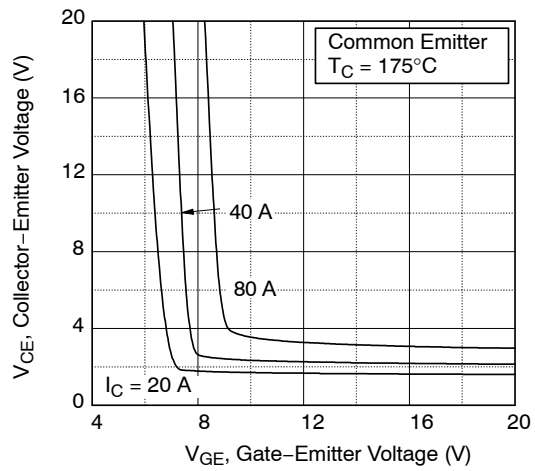


Figure 6. Saturation Voltage vs  $V_{GE}$

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

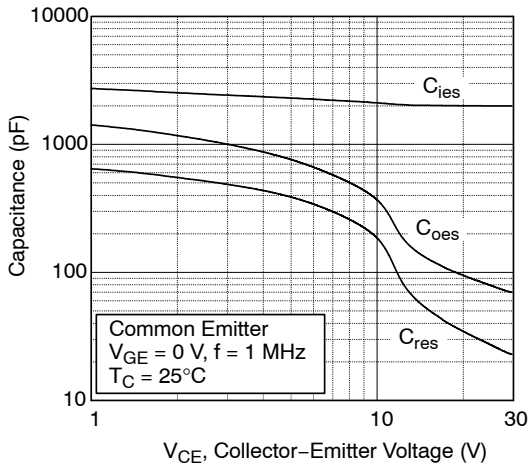


Figure 7. Capacitance Characteristics

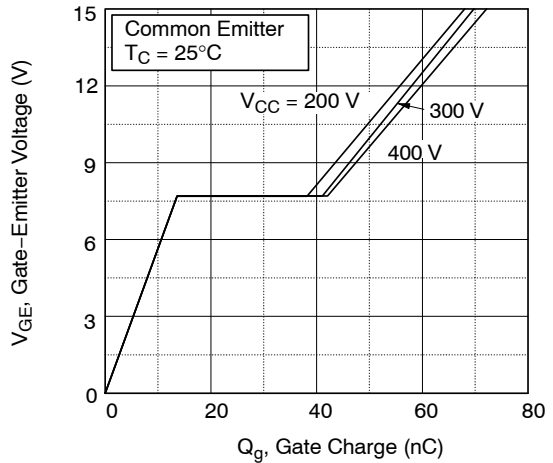


Figure 8. Gate Charge Characteristics

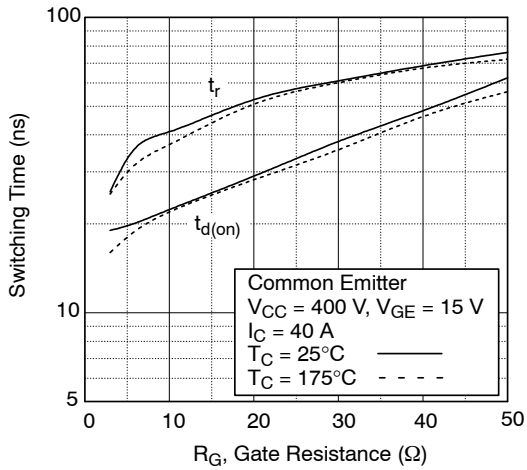


Figure 9. Turn-On Characteristics vs. Gate Resistance

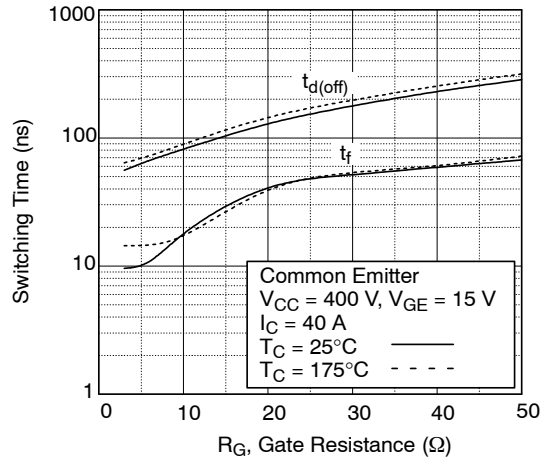


Figure 10. Turn-Off Characteristics vs. Gate Resistance

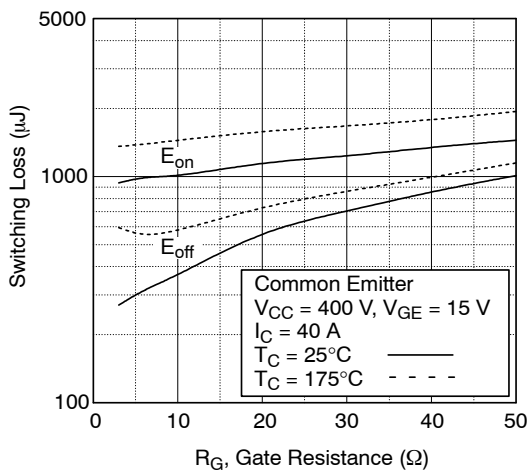


Figure 11. Switching Loss vs. Gate Resistance

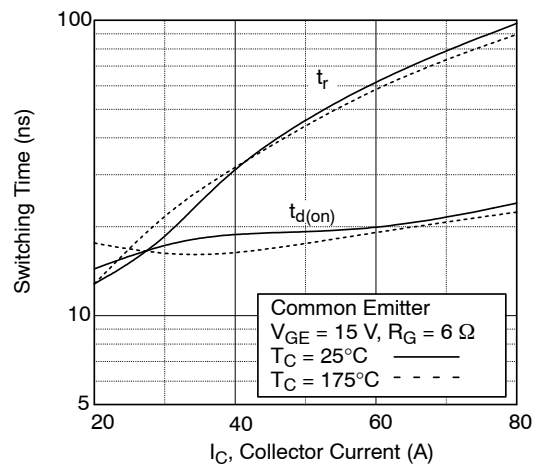
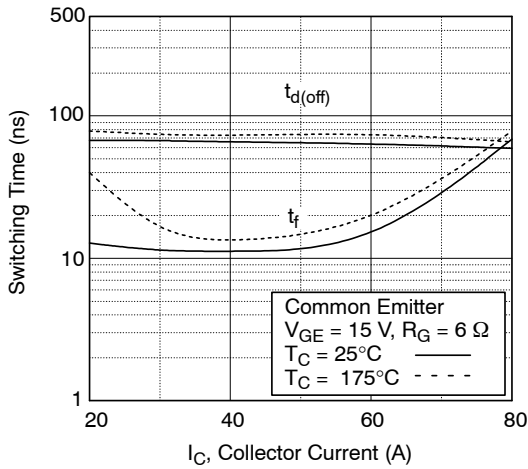


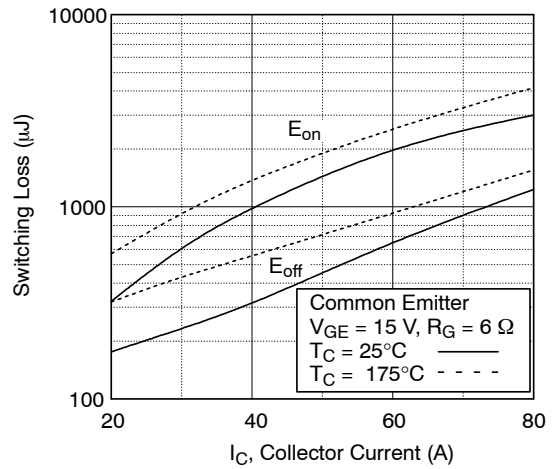
Figure 12. Turn-On Characteristics vs. Collector Current

# FGH40T65SH

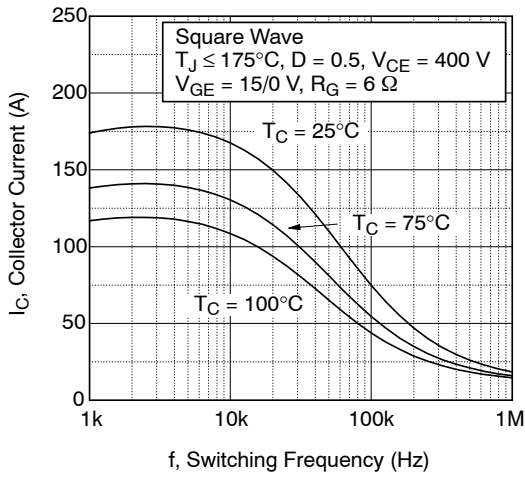
## TYPICAL PERFORMANCE CHARACTERISTICS (continued)



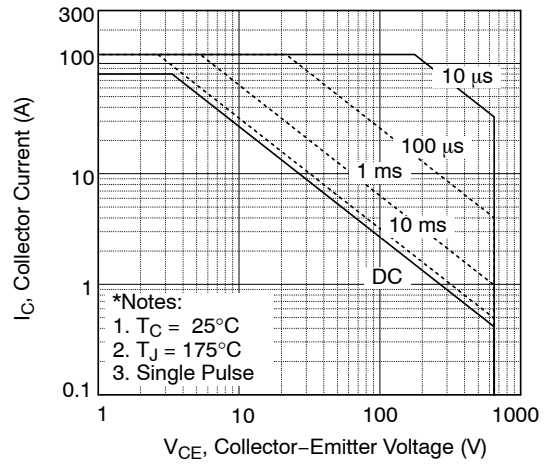
**Figure 13. Turn-Off Characteristics vs. Collector Current**



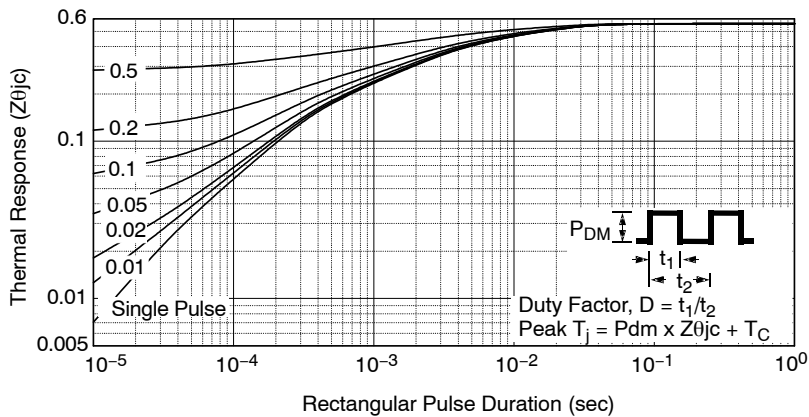
**Figure 14. Switching Loss vs. Collector Current**



**Figure 15. Load Current vs. Frequency**



**Figure 16. SOA Characteristics**



**Figure 17. Transient Thermal Impedance of IGBT**

# MECHANICAL CASE OUTLINE

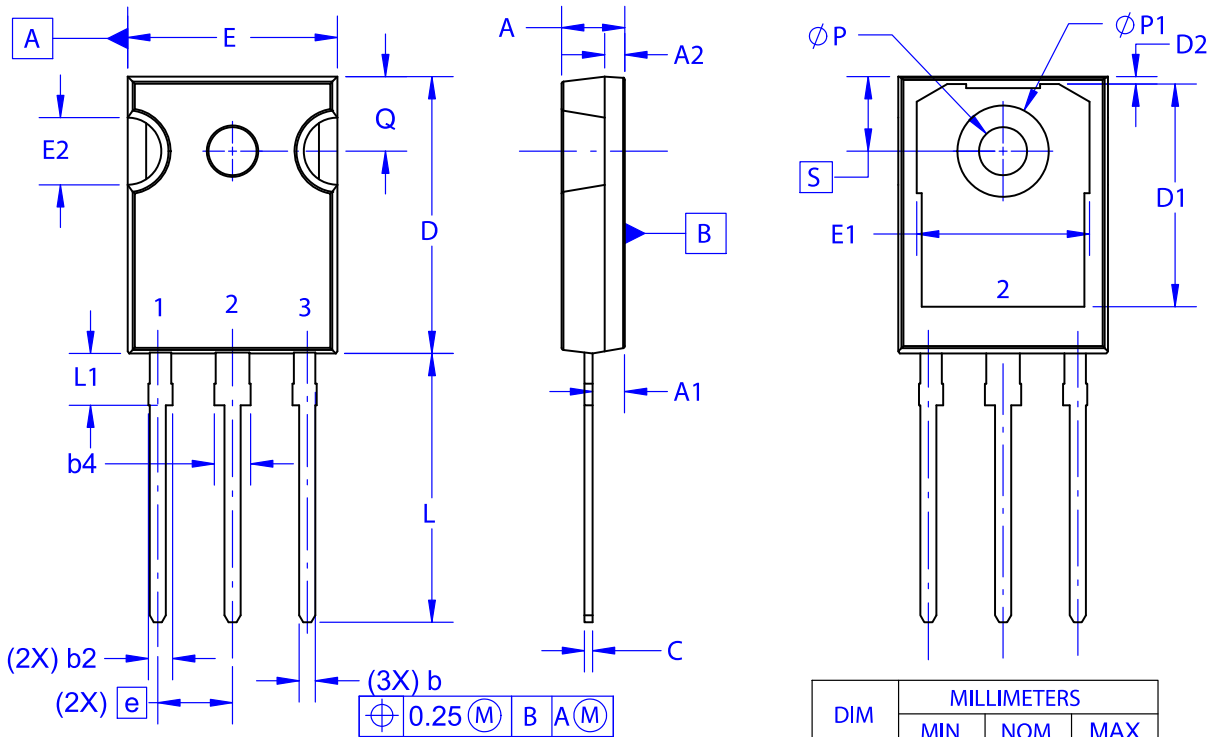
## PACKAGE DIMENSIONS

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TO-247-3LD  
CASE 340CH  
ISSUE A

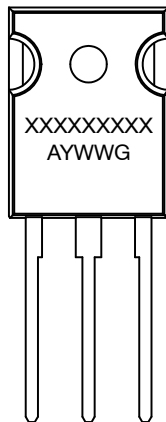
DATE 09 OCT 2019



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 - 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.58	4.70	4.82
A1	2.29	2.475	2.66
A2	1.40	1.50	1.60
D	20.32	20.57	20.82
E	15.37	15.62	15.87
E2	4.96	5.08	5.20
e	~	5.56	~
L	19.75	20.00	20.25
L1	3.69	3.81	3.93
∅P	3.51	3.58	3.65
Q	5.34	5.46	5.58
S	5.34	5.46	5.58
b	1.17	1.26	1.35
b2	1.53	1.65	1.77
b4	2.42	2.54	2.66
c	0.51	0.61	0.71
D1	13.08	~	~
D2	0.51	0.93	1.35
E1	12.81	~	~
∅P1	6.61	6.73	6.85

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